



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Hiroshi TAKANASHI et al.

Serial No. 09/838,118

Filed April 20, 2001

Confirmation No. 9938

Docket No. 2001-0476

Group Art Unit 1752

Examiner S. Lee

NEGATIVE-WORKING PHOTOSENSITIVE
RESIN COMPOSITION AND
PHOTOSENSITIVE RESIN PLATE USING
THE SAME

THE COMMISSIONER IS AUTHORIZED
TO CHARGE ANY DEFICIENCY IN THE
FEES FOR THIS PAPER TO DEPOSIT
ACCOUNT NO. 23-0975

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RESPONSE

Assistant Commissioner for Patents,
Washington, D.C.

Sir:

In response to the Official Action dated November 21, 2001, please amend the present application as follows:

IN THE CLAIMS:

Please amend claim 1 as follows:

1. (Amended) A photosensitive resin plate comprising a support having formed thereon directly or via an adhesive layer a photosensitive layer of from 0.45 to 0.8 mm in thickness comprising a negative working photosensitive resin composition consisting essentially of (A) a film-forming polymer, (B) an unsaturated compound having a radical polymerizable ethylenic double bond, (C) a photopolymerization initiator, (D) a thermal polymerization inhibitor, and (E) at least one member selected from compounds represented by following formula (I):

R^1-X (I)